PRODUCT CHANGE NOTICE

Manufacturing Site Change for Assembly of Intersil Ceramic Solder Seal Packaged Products

Refer to:
PCN11041

Date: April 8, 2011

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To: Our Valued Intersil Customer

Subject: **Manufacturing Site Change for Assembly of Intersil Ceramic Solder Seal Packaged Products –** *Amkor (ATP) Muntinlupa City, Philippines and Intersil (ISP) Palm Bay, FL*

This notice is to inform you that Intersil is qualifying the Amkor (ATP) and Intersil (ISP) facilities for performing assembly of the listed Ceramic Leadless Chip Carrier (CLCC), Ceramic Solder Seal Flatpack (CFP), and Ceramic Solder Seal Dual-In-Line (SBDIP) packaged products. This action will provide the capability and capacities for Intersil to meet customer's delivery requirements. The product and site-specific qualification activities at ATP are in progress and expected to complete during the next three to six months. The ISP facility is considered QBE (Qualified by Extension) as the existing package styles, processes, and materials used to assemble the affected products are qualified and in use in on-going manufacturing operations at the facility today.

Products affected:

CDP1802ACD3	HI1-574AKD-5	HI1-674AKD-5	HS4-3282-8
HI1-565AJD-5	HI1-574ASD-2	HS1-3182-8	HS4-3282R5307
HI1-565ATD-2	HI1-574ATD-2	HS1-3182-9+	
HI1-574AJD-5	HI1-574ATD-2S2035	HS4-3182-8	

The Amkor (ATP) and Intersil (ISP) facilities are ISO 9001:2008, TS 16949:2009, ISO 14001:2004, and currently QML Class Q certified assembly/test locations. The ATP facility is currently Intersil qualified for performing assembly operations for various package styles. The ISP facility is currently qualified for performing assembly operations for various package styles including the ceramic solder seal packages (CLCC, CFP, SBDIP) affected by this notice. There will be no change to the POD (package outline drawing), bond wire material, die attach material, package body, package lid, or final plating. The material set combinations for ceramic solder seal package assembly are as follows:

Material	**CFP**	**CLCC/SBDIP**	
Die Attach	Silver Polymer/ JM7000	Silver Polymer/ JM7000	Gold Eutectic
Bond Wire	1.25 mil Aluminum (Al)		
Seal	Gold-Tin (AuSn) Solder		

The assembly qualification plan for the ATP facility is designed using MIL-PRF-38535, JEDEC, and other applicable industry standards to confirm there is no impact to form, fit, function, or interchangeability of the product. A summary of the ATP qualification plan is included. The ISP facility is considered QBE (Qualified by Extension) as the existing package styles, processes, and materials used to assemble the affected products are qualified and in use in on-going manufacturing operations at the facility today. The remainder of the manufacturing operations (wafer fabrication, package level electrical testing, shipment, etc.) will continue to be processed to previously established conditions and systems.

Product affected by this change is identifiable via Intersil's internal traceability system. In addition, product assembled at ATP and ISP may be identified by the assembly site code (country of assembly) when marked on the devices. The site code for product assembled at ATP is "L" and ISP is "X".

Intersil will take all necessary actions to conform to agreed upon customer requirements and to ensure the continued high quality and reliability of Intersil products being supplied. Customers may expect to receive product assembled at either the current or the newly qualified sites beginning *ninety* days from the date of this notification or earlier with approval.

If you have concerns with this change notice, Intersil must hear from you promptly. Please contact the nearest Intersil Sales Office or call the Intersil Corporate line at 1-888-468-3774, in the United States, or 1-321-724-7143 outside of the United States.

Regards,

Jon Brewster

Jon Brewster
Intersil Corporation PCN11041

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PCN11041 – ATP Qualification Plan

Reliability Test	5962-8512704XA	5962-85131013A	HI1-565ASD/883
	28 LEAD SBDIP - POLYMER/JM7000	**28 LEAD CLCC - POLYMER/JM7000**	**24 LEAD SBDIP - Eutectic**
Subgroup B1	ss=3 from 1 lot	ss=3 from 1 lot	ss=3 from 1 lot
	Resistance to Solvents. MIL-PRF-38535 Group B Test Method 2015	Resistance to Solvents. MIL-PRF-38535 Group B Test Method 2015	Resistance to Solvents. MIL-PRF-38535 Group B Test Method 2015
Subgroup B2	ss=3 from 1 lot	ss=3 from 1 lot	ss=3 from 1 lot
	Die Shear Test or Stud Pull. MIL-PRF-38535 Group B Test Method 2019 or 2027	Die Shear Test or Stud Pull. MIL-PRF-38535 Group B Test Method 2019 or 2027	Die Shear Test or Stud Pull. MIL-PRF-38535 Group B Test Method 2019 or 2027
	ss=4 from 1 lot	ss=4 from 1 lot	ss=4 from 1 lot
	Wire Bond strength. MIL-PRF-38535 Group B Test Method 2011. 22 wires from 4 devices	Wire Bond strength. MIL-PRF-38535 Group B Test Method 2011. 22 wires from 4 devices	Wire Bond strength. MIL-PRF-38535 Group B Test Method 2011. 22 wires from 4 devices
Subgroup B3	ss=22 from 1 lot	ss=22 from 1 lot	ss=22 from 1 lot
	Solderability Lead Finish. MIL-PRF-38535 Group B Test Method 2003	Solderability Lead Finish. MIL-PRF-38535 Group B Test Method 2003	Solderability Lead Finish. MIL-PRF-38535 Group B Test Method 2003

PCN11041 – ATP Qualification Plan – cont.

Reliability Test	5962-8512704XA	5962-85131013A	HI1-565ASD/883
	28 LEAD SBDIP - POLYMER/JM7000	28 LEAD CLCC - POLYMER/JM7000	24 LEAD SBDIP - Eutectic
Subgroup D1	ss=15 from 1 lot	ss=15 from 1 lot	ss=15 from 1 lot
	a) Physical Dimensions	a) Physical Dimensions	a) Physical Dimensions
Subgroup D2	ss=15 from 1 lot	ss=15 from 1 lot	ss=15 from 1 lot
	a) Lead Integrity	a) Lead Integrity	a) Lead Integrity
	b) Seal Test (Fine & Gross Leak)	b) Seal Test (Fine & Gross Leak)	b) Seal Test (Fine & Gross Leak)
Subgroup D3	ss=15 from 1 lot	ss=15 from 1 lot	ss=15 from 1 lot
	a) Thermal Shock	a) Thermal Shock	a) Thermal Shock
	b) Temp Cycle (100)	b) Temp Cycle (100)	b) Temp Cycle (100)
	c) Moisture Resist	c) Moisture Resist	c) Moisture Resist
	d) Visual Inspection	d) Visual Inspection	d) Visual Inspection
	e) Seal Test (Fine & Gross Leak)	e) Seal Test (Fine & Gross Leak)	e) Seal Test (Fine & Gross Leak)
	f) Electrical	f) Electrical	f) Electrical
Subgroup D4	ss=15 from 1 lot	ss=15 from 1 lot	ss=15 from 1 lot
	a) Mechanical Shock	a) Mechanical Shock	a) Mechanical Shock
	b) Vibration	b) Vibration	b) Vibration
	c) Constant Acc.	c) Constant Acc.	c) Constant Acc.
	d) Seal Test (Fine & Gross Leak)	d) Seal Test (Fine & Gross Leak)	d) Seal Test (Fine & Gross Leak)
	e) Visual Inspection	e) Visual Inspection	e) Visual Inspection
	f) Electrical	f) Electrical	f) Electrical
Subgroup D5	ss=15 from 1 lot	ss=15 from 1 lot	ss=15 from 1 lot
	a) Salt Atmosphere	a) Salt Atmosphere	a) Salt Atmosphere
	b) Visual Inspection	b) Visual Inspection	b) Visual Inspection
	c) Seal Test (Fine & Gross Leak)	c) Seal Test (Fine & Gross Leak)	c) Seal Test (Fine & Gross Leak)
Subgroup D6	ss=3 from 1 lot	ss=3 from 1 lot	ss=3 from 1 lot
	Internal Water Vapor	Internal Water Vapor	Internal Water Vapor
Subgroup D7	ss=15 from 1 lot	Not Applicable no leads	ss=15 from 1 lot
	Adhesion of Lead Finish		Adhesion of Lead Finish
Subgroup D8	Not required for solder seal parts	Not required for solder seal parts	Not required for solder seal parts